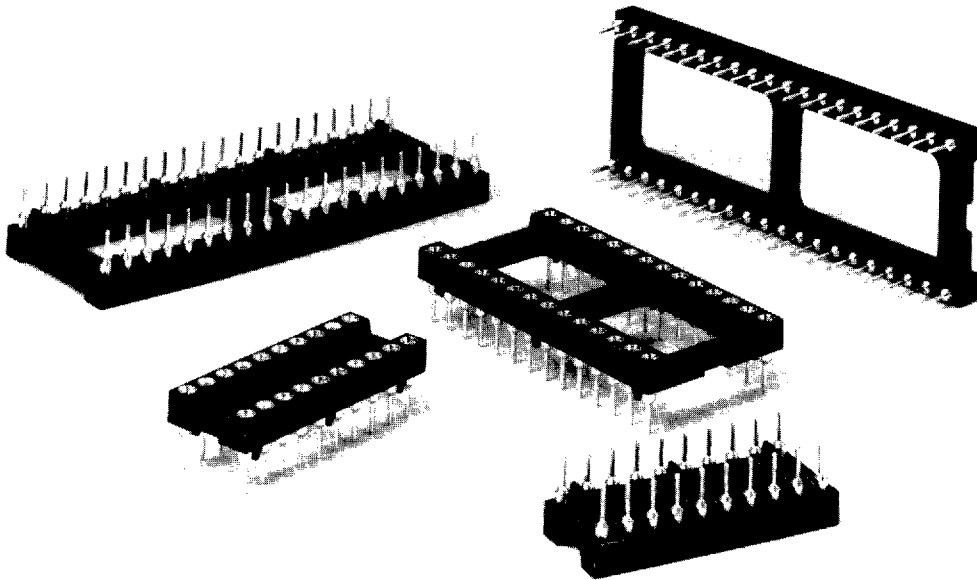


Precision I.C. "Standoff" Sockets



Garry's new IC sockets with "standoffs" keep the pins from sealing off the plated-through holes in PC boards, eliminating gas entrapment. The standoffs keep the socket an average distance of .060" above the PC board, making it easier for aqueous flushing of the flux after soldering. It ensures a superior solder joint by eliminating gas entrapment in the plated-through holes.

Two, three or four standoffs are built into the side of each socket, depending on the pin count, which ranges from eight to forty.

Garry offers standoffs with its full range of precision IC sockets, which are available with a variety of mounting options and feature hi-rel sockets with Swiss screw machine mounting terminals.

Features of

Garry's "Standoff" Sockets include:

- Open frame construction with standoffs for superior IC cooling, better cleaning and easier inspection.
- Can accept leads as short as .090"
- Four-fingered Beryllium copper contact for high reliability
- Precision machined outer sleeve with closed bottom eliminates solder wicking problems
- Insulator dimensions permit end-to-end or side-to-side spacing

Materials:

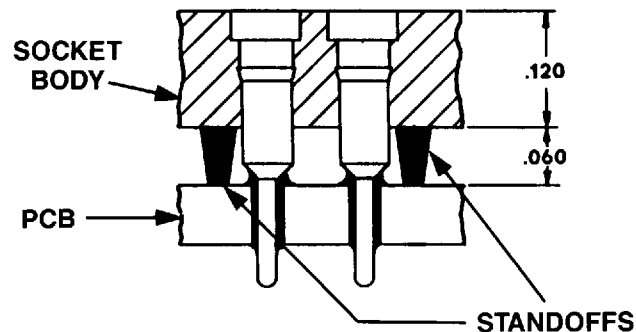
Insulator: Glass reinforced thermoplastic polyester, rated UL 94V-0 (color: black)

Spring Contact: Beryllium copper

Outer Sleeve: Hard Brass

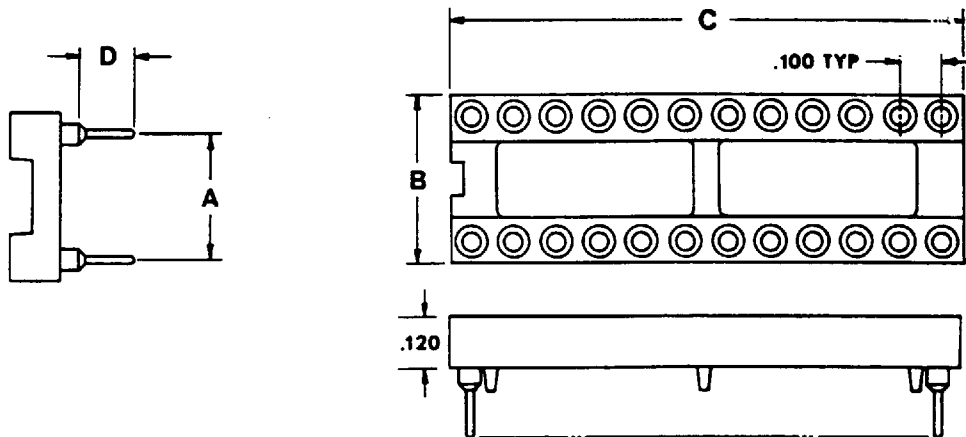
Optional sleeve hardness

¼ Hard available, consult factory.



 Garry Electronics

Precision I.C. "Standoff" Sockets



XXX-XX - XX - X

SERIES-PIN COUNT				
	# OF PINS	A DIM. (in.)	B DIM. (in.)	C DIM. (in.)
612-08	8	.300	.399	.399
612-14	14	.300	.399	.699
612.16	16	.300	.399	.799
612.18	18	.300	.399	.899
612.20	20	.300	.399	.999
612.24	24	.300	.399	1.199
631.24	24	.600	.699	1.999
631.28	28	.600	.699	1.399
631-40	40	.600	.699	1.999

PIN STYLE		
	DESCRIPTION	D DIM.(in.)
CS	Solder tail for .062 thick board	.104
CC	Solder tail for .062 thick board	.128
CJ	Solder tail for .093 or .125 thick board	.178

PIN PLATING			
	CONTACT	SLEEVE	THICKNESS (μ)
B	Gold	Gold	30/10
D	Gold	Tin	30/200
E	Tin	Tin	150/200
S	Gold	Tin/Lead	30/200
L	Gold	Tin	10/200

For additional platings consult factory rep.

Typical Performance Characteristics:

Contact Resistance	10 Milliohms Maximum
Contact Rating	3 Amps
Capacitance (Contact to Contact)	1.0 pF per MIL-STD-202 Method 305
Vibration	Passed MIL-STD-1344 Method 2005.1, Condition III, 15Gs
Shock	Passed MIL-STD-1344 Method 2004.1, Condition G, 100Gs
Insulation Resistance	2 x 10 ⁶ Megohms per MIL-STD-1344 Method 3003.1
Dielectric Withstanding Voltage (DWV)	1000 VAC (RMS) per MIL-STD-1344 Method 3001.1
Operating Temperature	- 55°C to + 125°C
Normal Force	105 Grams Min. With .018" Dia. Polished Steel Pin (Typ.)
Inner Contact Retention	7.5 Lbs. per Line Average
Sleeve Retention In Plastic	3.0 Lbs. per Line Minimum
Solderability	Passed MIL-STD-202 Method 208
Insertion Force	214 Grams (7.5 oz.) Average With .018" Dia. Polished Steel Pin
Withdrawal Force	94 Grams (3.3 oz.) Average With .018" Dia. Polished Steel Pin

